

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A peeling method comprising:
forming a metal layer over a substrate;
forming an oxide layer contacting with the metal layer;
forming an insulating film contacting with the oxide layer;
forming a semiconductor film having an amorphous structure, ~~and including hydrogen on~~ over the insulating film, wherein the semiconductor film comprises hydrogen;
performing heat treatment for diffusing the hydrogen;
adhering a support member to a layer to be peeled, wherein the layer comprises including the oxide layer, the insulating film and the semiconductor film; and
peeling the layer to be peeled ~~adhered to the support member~~ from the metal layer formed over the substrate by means of physical means after adhering the support member.
2. (Currently Amended) A peeling method comprising:
forming a metal layer over a substrate;
forming an oxide layer contacting with the metal layer;
forming an insulating film contacting with the oxide layer;
forming a semiconductor film having an amorphous structure, ~~and including hydrogen on~~ over the insulating film, wherein the semiconductor film comprises hydrogen;
performing heat treatment for diffusing the hydrogen;

forming a thin film transistor comprising the semiconductor film as an active layer and an element connected with the thin film transistor;

adhering a support member to a layer to be peeled, wherein the layer comprises including the oxide layer, the insulating film, the thin film transistor and the element connected with the thin film transistor; and

peeling the layer to be peeled ~~adhered to the support member~~ from the metal layer formed over the substrate by means of physical means after adhering the support member.

3. (Withdrawn) A peeling method comprising:

forming a first metal layer over a substrate;

forming an oxide layer contacting with the first metal layer;

forming an insulating film contacting with the oxide layer;

forming a second metal layer including hydrogen on the insulating film;

performing heat treatment for diffusing hydrogen;

forming a thin film transistor and an element connected with the thin film transistor; and

adhering a support member to a layer to be peeled including the oxide layer, the insulating film, the thin film transistor and the element; and

peeling the layer to be peeled adhered to the support member from the first metal layer formed over the substrate by means of physical means.

4. (Currently Amended) A peeling method comprising:

forming a metal layer including hydrogen over a ~~[[the]]~~ substrate;

forming an oxide layer contacting with the metal layer;

forming an insulating film in contact with the oxide layer;

forming a semiconductor film having an amorphous structure, ~~and including hydrogen on~~ over the insulating film;

performing heat treatment for diffusing the hydrogen;
forming a thin film transistor including the semiconductor film as an active layer
and an element connected with the thin film transistor; and
adhering a support member to a layer to be peeled, wherein the layer comprises
~~including the oxide layer,~~ the insulating film, the thin film transistor and the element; and
peeling the layer to be peeled ~~adhered to the support member~~ from the metal
layer formed over the substrate by means of physical means after adhering the support
member.

5. (Currently Amended) A peeling method according to claim 1, wherein the
heat treatment is performed at a temperature equal to or higher than a temperature at
which the hydrogen in ~~[[a]]~~ the semiconductor film is emitted or diffused.

6. (Currently Amended) A peeling method according to claim 2, wherein the
heat treatment is performed at a temperature equal to or higher than a temperature at
which the hydrogen in ~~[[a]]~~ the semiconductor film is emitted or diffused.

7. (Withdrawn) A peeling method according to claim 3, wherein the heat
treatment is performed at a temperature equal to or higher than a temperature at which
hydrogen in a film is emitted or diffused.

8. (Currently Amended) A peeling method according to claim 4, wherein the
heat treatment is performed at a temperature equal to or higher than a temperature at
which the hydrogen in ~~a film~~ the metal layer is emitted or diffused.

9. (Original) A peeling method according to claim 1, wherein the metal layer is a
single layer comprised of an element selected from the group consisting of W, Ti, Ta,
Mo, Cr, Nd, Fe, Ni, Co, Zr, Zn, Ru, Rh, Pd, Os, Ir, and Pt or an alloy material or

compound material that contains the element as its main constituent, or is a lamination layer comprised of the metals or mixtures thereof.

10. (Original) A peeling method according to claim 2, wherein the metal layer is a single layer comprised of an element selected from the group consisting of W, Ti, Ta, Mo, Cr, Nd, Fe, Ni, Co, Zr, Zn, Ru, Rh, Pd, Os, Ir, and Pt or an alloy material or compound material that contains the element as its main constituent, or is a lamination layer comprised of the metals or mixtures thereof.

11. (Withdrawn) A peeling method according to claim 3, wherein the metal layer is a single layer comprised of an element selected from the group consisting of W, Ti, Ta, Mo, Cr, Nd, Fe, Ni, Co, Zr, Zn, Ru, Rh, Pd, Os, Ir, and Pt or an alloy material or compound material that contains the element as its main constituent, or is a lamination layer comprised of the metals or mixtures thereof.

12. (Original) A peeling method according to claim 4, wherein the metal layer is a single layer comprised of an element selected from the group consisting of W, Ti, Ta, Mo, Cr, Nd, Fe, Ni, Co, Zr, Zn, Ru, Rh, Pd, Os, Ir, and Pt or an alloy material or compound material that contains the element as its main constituent, or is a lamination layer comprised of the metals or mixtures thereof.

13. (Original) A peeling method according to claim 1, wherein the oxide layer is a silicon oxide film formed by sputtering.

14. (Original) A peeling method according to claim 2, wherein the oxide layer is a silicon oxide film formed by sputtering.

15. (Withdrawn) A peeling method according to claim 3, wherein the oxide layer is a silicon oxide film formed by sputtering.

16. (Original) A peeling method according to claim 4, wherein the oxide layer is a silicon oxide film formed by sputtering.

17. (Currently Amended) A peeling method according to claim 1, wherein the insulating film is at least one selected from the group consisting of a silicon oxide film, a silicon oxynitride film, and [[or]] a lamination layer of the films.

18. (Original) A peeling method according to claim 2, wherein the insulating film is a silicon oxide film, a silicon oxynitride film, or a lamination layer of the films.

19. (Withdrawn) A peeling method according to claim 3, wherein the insulating film is a silicon oxide film, a silicon oxynitride film, or a lamination layer of the films.

20. (Currently Amended) A peeling method according to claim 4, wherein the insulating film is at least one selected from the group consisting of a silicon oxide film, a silicon oxynitride film, and [[or]] a lamination layer of the films.

21. (Original) A peeling method according to claim 1, wherein a thickness of the oxide layer is thicker than a film thickness of the metal layer.

22. (Original) A peeling method according to claim 2, wherein a thickness of the oxide layer is thicker than a film thickness of the metal layer.

23. (Withdrawn) A peeling method according to claim 3, wherein a thickness of the oxide layer is thicker than a film thickness of the metal layer.

24. (Original) A peeling method according to claim 4, wherein a thickness of the oxide layer is thicker than a film thickness of the metal layer.

25. (Currently Amended) A peeling method according to claim 2, wherein an element provided on the insulating film is at least one selected from the group consisting of a light emitting element, a semiconductor element, and [[or]] a liquid crystal element.

26. (Withdrawn) A peeling method according to claim 3, wherein an element provided on the insulating film is a light emitting element, a semiconductor element, or a liquid crystal element.

27. (Currently Amended) A peeling method according to claim 4, wherein an element provided on the insulating film is at least one selected from the group consisting of a light emitting element, a semiconductor element, and [[or]] a liquid crystal element.